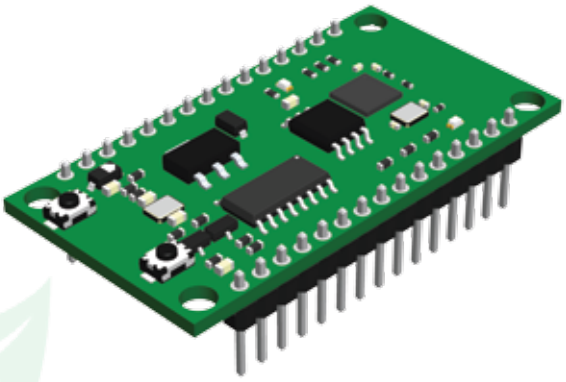


WIFI MODULE

FEATURES

- IEEE® 802.11 b/g/n 20 MHz (1x1) solution
 - Single spatial stream in 2.4 GHz ISM band
 - Integrated Transmit/Receive switch
 - Integrated PCB antenna or u.FL micro co-ax connector for external antenna
 - Superior sensitivity and range via advanced PHY signal processing
 - Advanced equalization and channel estimation
 - Advanced carrier and timing synchronization
 - Wi-Fi® Direct (supported till firmware release 19.5.2)
 - Soft-AP support
 - Supports IEEE 802.11 WEP, WPA, WPA2 security
 - Support Enterprise security with WPA/WPA2 (802.1X)
 - EAP-TLS
 - EAP-PEAPv0/1 with TLS
 - EAP-TTLSv0 with MSCHAPv2
 - EAP-PEAPv0/1 with MSCHAPv2
 - Superior MAC throughput via hardware accelerated two-level A-MSDU/A-MPDU frame aggregation and block acknowledgment
 - On-chip memory management engine to reduce host load
 - SPI host interface
 - Operating temperature range from -40°C to +85°C. RF performance at room temperature of 25°C with a 2-3 db change at boundary conditions
 - I/O operating voltage of 2.7V to 3.6V
 - Built-in 26 MHz crystal
 - Integrated Flash memory for system software
 - Power Save modes
 - 4 µA Power-Down mode typical at 3.3V I/O
 - 380 µA Doze mode with chip settings preserved (used for beacon monitoring)
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 - On-chip low power sleep oscillator
 - Fast host wake-up from Doze mode by a pin or SPI transaction
 - Fast Boot options
 - On-chip boot ROM (Firmware instant boot)
 - SPI flash boot
 - Low-leakage on-chip memory for state variables
 - Fast AP re-association (150 ms)
 - On-chip Network stack to offload MCU
 - Integrated Network IP stack to minimize host CPU requirements
 - Network features TCP, UDP, DHCP, ARP, HTTP, TLS, and DNS
 - Hardware accelerators for Wi-Fi and TLS security to improve connection time
 - Hardware accelerator for IP checksum
 - Hardware accelerators for OTA security
 - Small footprint host driver
- Remarks:** * Specification are subject to change without notice.
Image shown are just indicative